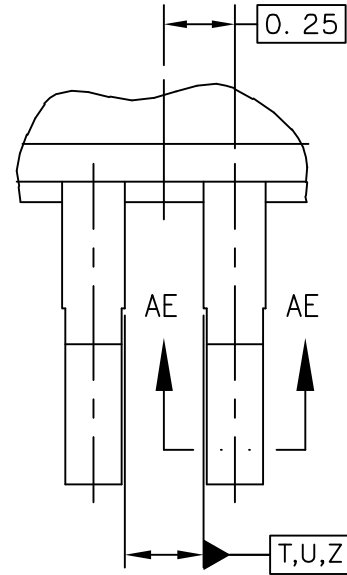
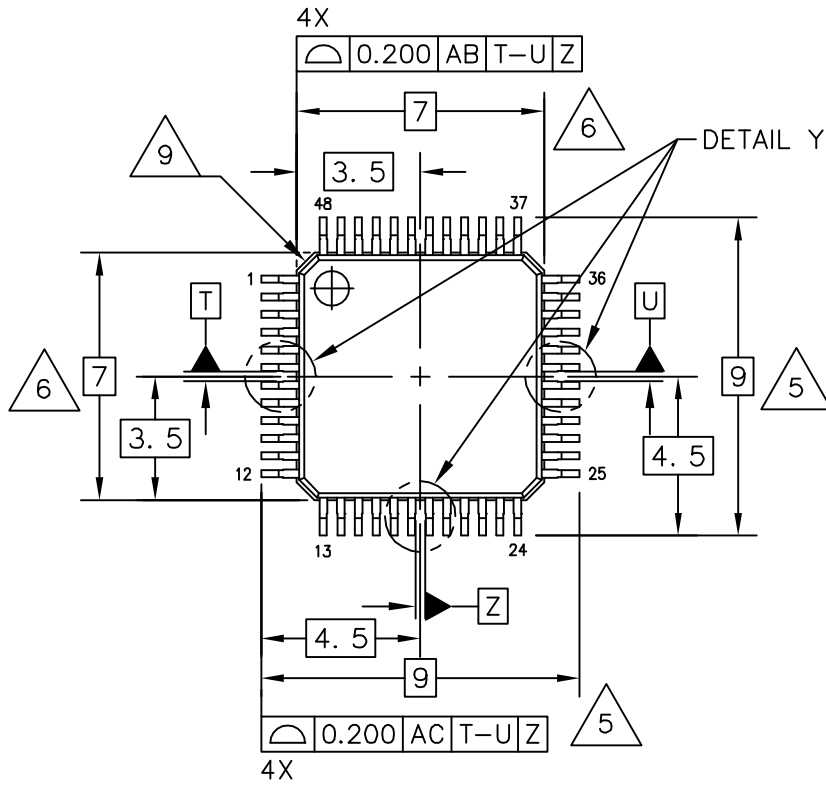




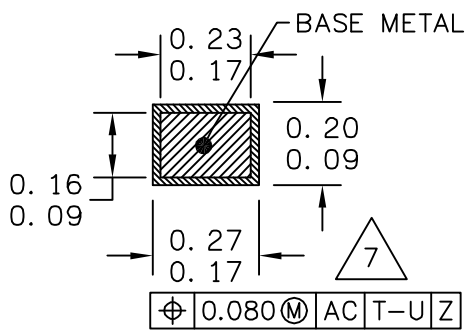
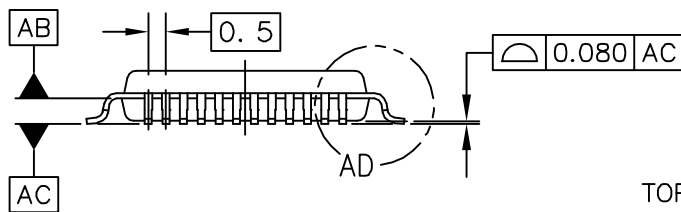
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# MECHANICAL OUTLINE

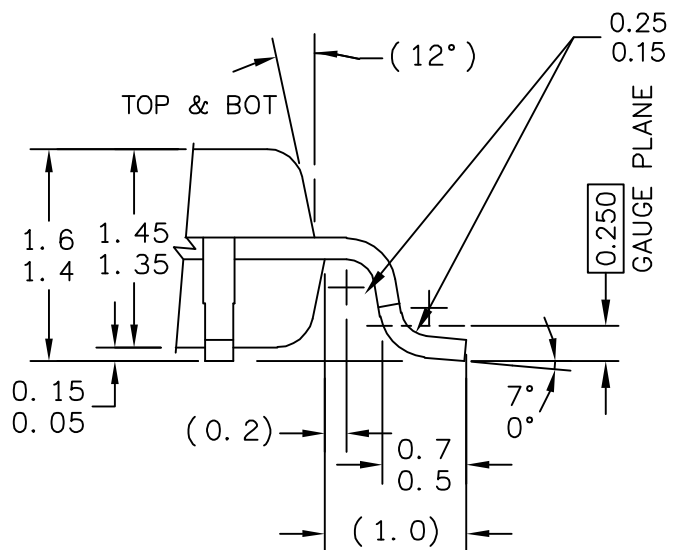
DO NOT SCALE THIS DRAWING



DETAIL Y



SECTION AE-AE



DETAIL AD

TITLE:  
 LQFP, 48 LEAD, 0.50 PITCH  
 (7.0 X 7.0 X 1.4)

DOCUMENT NO: 98ASH00962A REV: H

STANDARD: JEDEC MS-026-BBC

SOT313-3

SHEET: 1 OF 3



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# MECHANICAL OUTLINE

DO NOT SCALE THIS DRAWING

## NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DATUM PLANE AB IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DATUMS T, U, AND Z TO BE DETERMINED AT DATUM PLANE AB.



5. DIMENSIONS TO BE DETERMINED AT SEATING PLANE AC.



6. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.250 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE AB.



7. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.350.

8. MINIMUM SOLDER PLATE THICKNESS SHALL BE 0.0076.



9. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

TITLE:  
LQFP, 48 LEAD, 0.50 PITCH  
(7.0 X 7.0 X 1.4)

DOCUMENT NO: 98ASH00962A REV: H

STANDARD: JEDEC MS-026-BBC

SOT313-3 SHEET: 2



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# REVISION HISTORY

LTR	ORIGINATOR	REVISIONS	DRAFTER	DATE
F	--	--	--	23 FEB 2000
G	KAELIN WANG	UPDATED TO FREESCALE FORMAT.	K. WANG	14 APR 2005
H	LUCY BAI	UPDATED LOGO TO NXP (DAR #25182)	CS	19 JAN 2016

TITLE:  
LQFP, 48 LEAD, 0.50 PITCH  
(7.0 X 7.0 X 1.4)

DOCUMENT NO: 98ASH00962A      REV: H

STANDARD: JEDEC MS-026-BBC

SOT313-3      SHEET: 3